



Material Content Data Sheet



Sales Product Name				BSC050N03LS G		Issued		24. January 2018	
MA#				MA001823646					
Package				PG-TDSON-8-14		Weight*		118.94 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.213	1.02	1.02	10194	10194	
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		82		
	non noble metal	zinc	7440-66-6	0.039	0.03		327		
	non noble metal	iron	7439-89-6	0.778	0.65		6541		
wire	non noble metal	copper	7440-50-8	31.590	26.56	27.25	265587	272537	
	non noble metal	copper	7440-50-8	0.058	0.05	0.05	484	484	
	encapsulation	organic material	carbon black	1333-86-4	0.239	0.20		2011	
plating	plastics	epoxy resin	-	7.414	6.23		62334		
	inorganic material	silicondioxide	60676-86-0	40.181	33.80	40.23	337811	402156	
	non noble metal	tin	7440-31-5	1.243	1.04	1.04	10447	10447	
solder	noble metal	silver	7440-22-4	0.037	0.03	0.03	315	315	
	non noble metal	tin	7440-31-5	0.028	0.02		237		
	noble metal	silver	7440-22-4	0.035	0.03		296		
heatspreader	non noble metal	lead	7439-92-1	1.345	1.13	1.18	11310	11843	
	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
	non noble metal	zinc	7440-66-6	0.021	0.02		180		
	non noble metal	iron	7439-89-6	0.428	0.36		3594		
heat sink CLIP	non noble metal	copper	7440-50-8	17.360	14.60	14.98	145950	149769	
	inorganic material	phosphorus	7723-14-0	0.005	0.00		43		
	non noble metal	iron	7439-89-6	0.017	0.01		142		
*deviation	non noble metal	copper	7440-50-8	16.898	14.21	14.22	142070	142255	
						Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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